

PCN# 20190110000.1
Transfer of select P2-XMOS devices from GFAB to DFAB Wafer Fab site
Change Notification / Sample Request

Date: January 15, 2019
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services




20190110000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM629M-8/NOPB	null
LM629M-6/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190110000.1		PCN Date:	Jan 15, 2019	
Title:	Transfer of select P2-XMOS devices from GFAB to DFAB Wafer Fab site				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	Apr 15, 2019		Estimated Sample Availability:	Date provided at sample request.	
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input checked="" type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
PCN Details					
Description of Change:					
This change notification is to announce the transfer of select P2-XMOS devices from GFAB to the DFAB (DL-LIN) Wafer Fab site for the selected devices listed in the "Product Affected" section.					
Current Fab Site			New Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
GFAB6	P2-XMOS	150 mm	DL-LIN	P2-XMOS	200 mm
GFAB6 Die Metallization			DL-LIN Die Metallization		
12kA - Al 0.5%Cu			16kA - Al 0.5%Cu		
Qual details are provided in the Qual Data Section.					
Reason for Change:					
Greenock, Scotland (GFAB) Wafer Fab site closure					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Current:					
Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
GFAB6	GF6	GBR	Greenock		
New Fab Site:					
New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
DL-LIN	DLN	USA	Dallas		
Sample product shipping label (not actual product label)					
 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20:		 G4		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0055517 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS	
MSL 2 / 260C / 1 YEAR SEAL DT MSL 1 / 235C / UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L) TO: 1750					
Product Affected:					
LM629M-6/NOPB	LM629M-8/NOPB	LM629MX-8/NOPB	LM629MX-8/S7002371		
LM629M-8					

Qualification Report

Approve Date 08-January-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM629M-8/NOPB	QBS Process Reference: TLV9002ID
AC	Autoclave (121C, 2atm)	96 Hours	1/77/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	1/800	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0
HBM	ESD - HBM	1000 V	3/9/0	3/9/0
CDM	ESD - CDM	1000 V	3/9/0	3/9/0
HTOL	Life Test, 125C	300 Hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	1/77/0	3/231/0
LU	Latch-up	(per JESD78)	3/18/0	3/18/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	3/231/0

- QBS: Qual By Similarity

- Qual Device LM629M-8/NOPB is qualified at LEVEL3-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com